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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
19010696	12/05/2001	257	758	2811	Guana Vu

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\*\*CONTINUING DATA VERIFIED:

\*\*FOREIGN APPLICATIONS VERIFIED:

PG-PUB DO NOT PUBLISH ☒

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no  
35 USC 119 conditions met ☐ yes ☐ no  
Verified and Acknowledged Examiner's initials

ATTORNEY DOCKET NO.  
072219-0261614 (P05088)

TITLE: Multilevel metal interconnect and method of forming the interconnect with capacitive structures that adjust the capacitance of the interconnect

U.S. DEPT. OF COMMERCE, PATENT & TRADEMARK OFFICE

NOTES OF ALLOWANCE MAILED		CLASS ALLOWED	
Amount Due: Date Paid:		Primary Examiner	
DISCLAIMER		Prepared for Issue	
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